



30V N-Channel MOSFETs

General Description

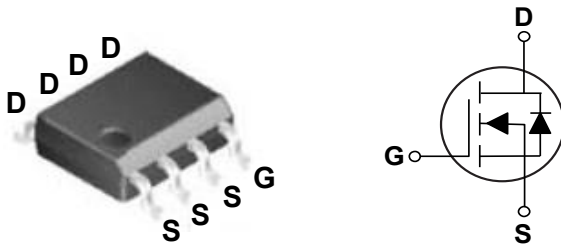
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)}$	I_D
30 V	8.5 mΩ	15 A

Features

- $R_{DS(ON)} \leq 8.5m\Omega @ V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

SOP-8 Pin Configuration



Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

Absolute Maximum Ratings $T_C=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current - Continuous ($T_C=25^\circ C$)	15	A
	Drain Current - Continuous ($T_C=100^\circ C$)	9.5	A
I_{DM}	Drain Current - Pulsed (NOTE 1)	60	A
P_D	Power Dissipation ($T_C=25^\circ C$)	4	W
	Power Dissipation - Derate above $25^\circ C$	0.032	W/ $^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
Marking Code		NC8P5	

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	85	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	31	$^\circ C/W$

**Electrical Characteristics (T_J=25°C, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =24V, V _{GS} =0V, T _J =125°C	---	---	10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =15A	---	---	8.5	mΩ
		V _{GS} =4.5V, I _D =8A	---	---	11	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.6	2.5	V
gfs	Forward Transconductance	V _{DS} =10V, I _D =8A	---	22	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _D =1A	---	23.2	---	nC
Q _{gs}	Gate-Source Charge		---	3.2	---	
Q _{gd}	Gate-Drain Charge		---	3.7	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =10V, V _{GS} =10V, R _{GEN} =2.7Ω, I _D =30A	---	7	---	nS
T _r	Rise Time		---	76.6	---	
T _{d(off)}	Turn-Off Delay Time		---	27.1	---	
T _f	Fall Time		---	52.6	---	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, F=1MHz	---	1180	---	pF
C _{oss}	Output Capacitance		---	177	---	
C _{rss}	Reverse Transfer Capacitance		---	132	---	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	3.2	---	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	15	A
I _{SM}	Pulsed Source Current (NOTE 3)		---	---	30	A
V _{SD}	Diode Forward Voltage (NOTE 3)	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



Characteristics Curves

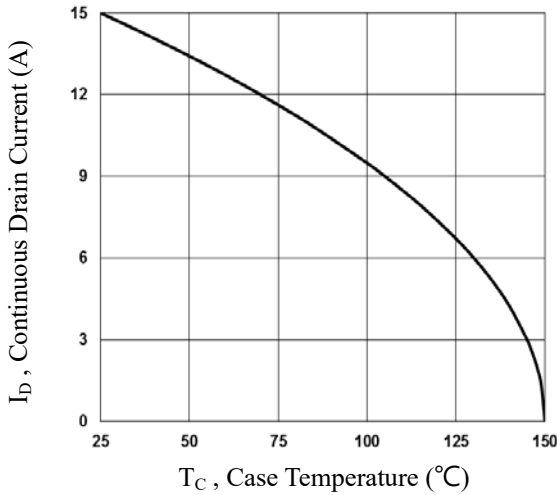


Fig.1 Continuous Drain Current vs. T_C

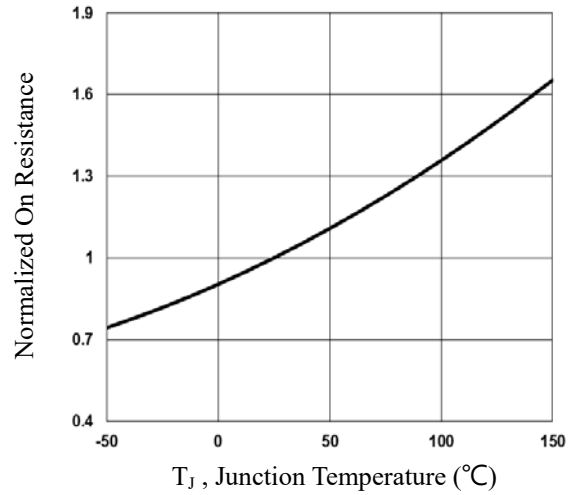


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

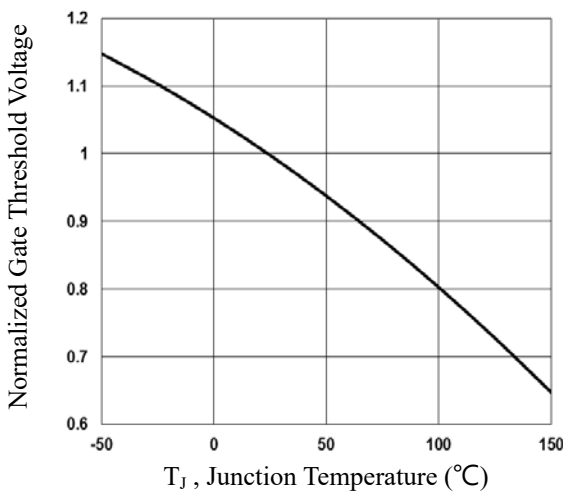


Fig.3 Normalized V_{th} vs. T_J

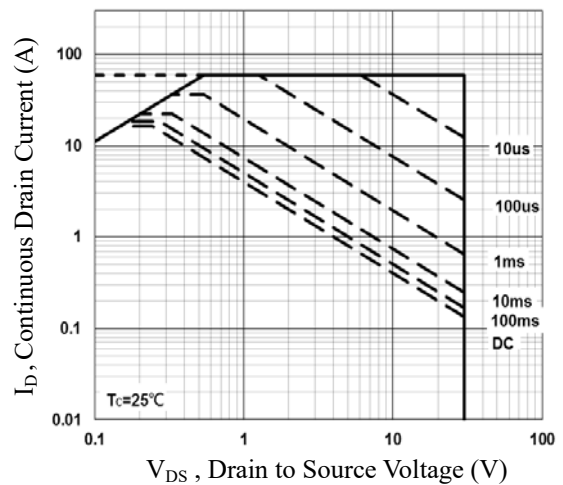


Fig.4 Maximum Safe Operation Area

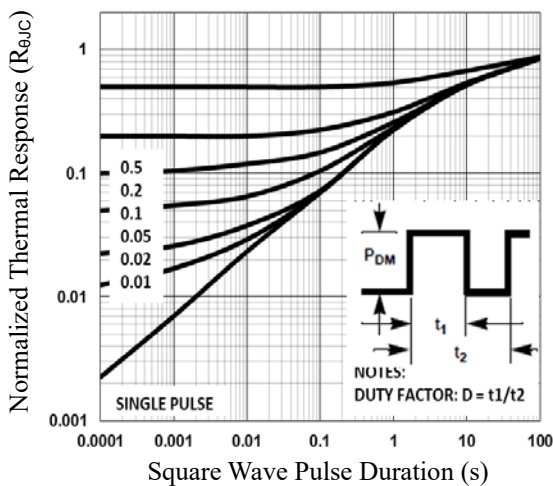


Fig.5 Normalized Transient Impedance

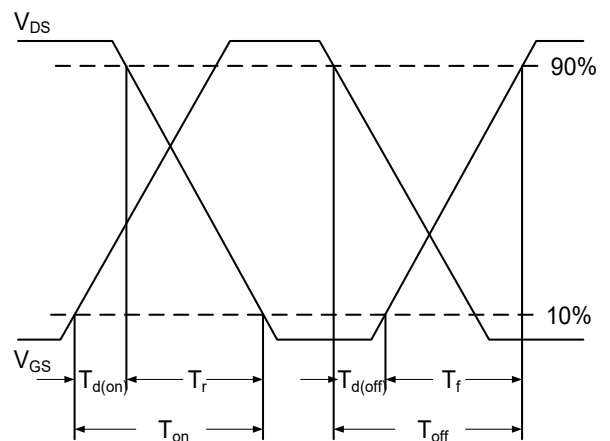


Fig.6 Switching Time Waveform



Characteristics Curves

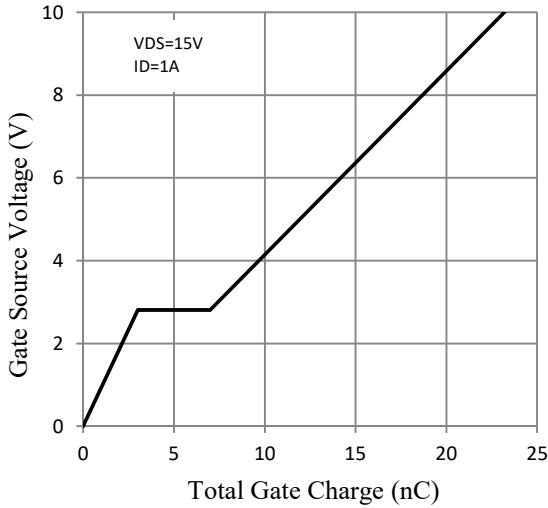
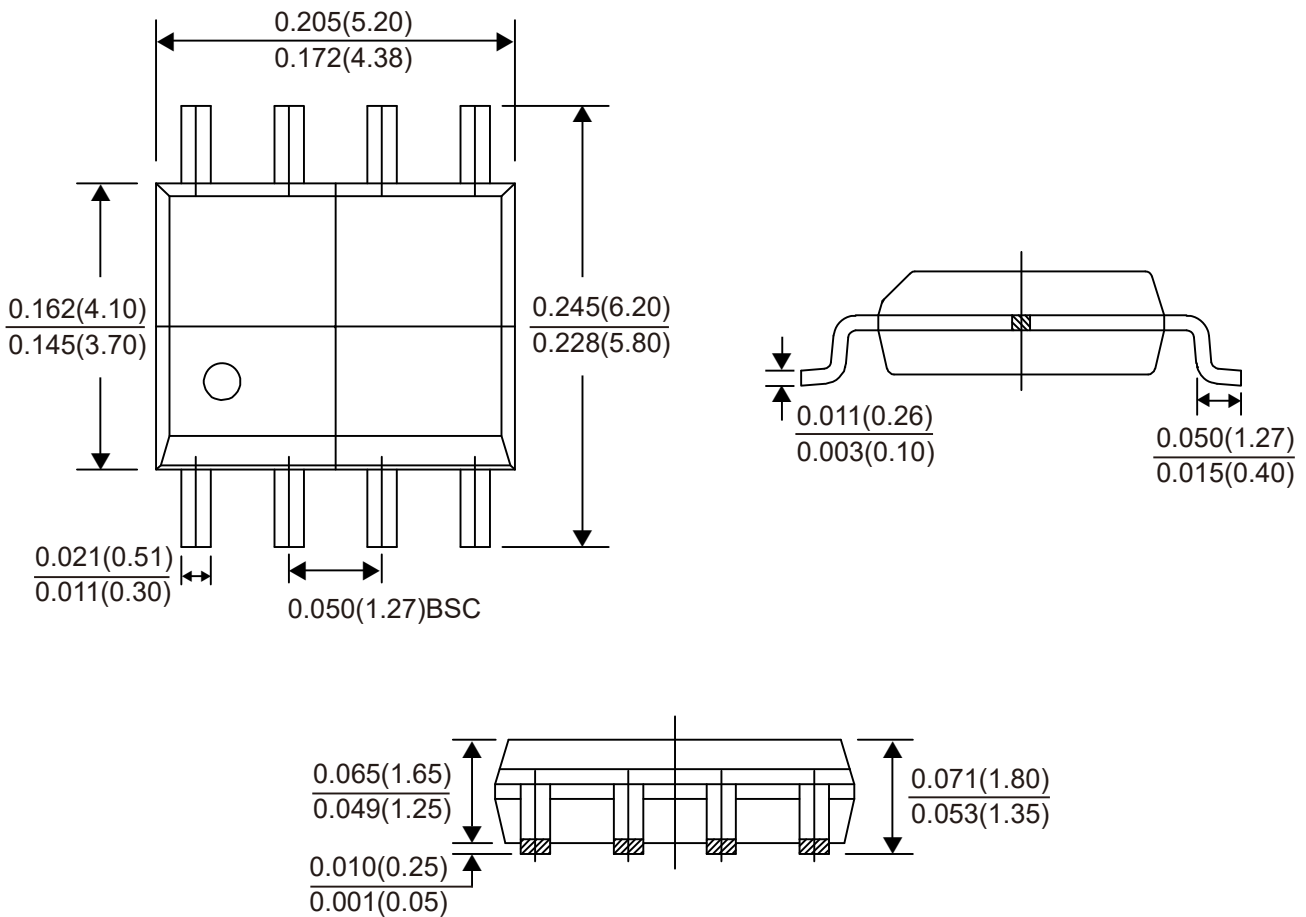


FIG. 7 Gate Charge Characteristics

Package Outline Dimensions



SOP-8

Dimensions in inches and (millimeters)



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